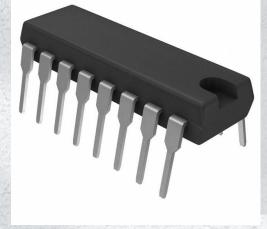


MC74HC4051ANG Datasheet

www.digi-electronics.com



DiGi Electronics Part Number	MC74HC4051ANG-DG
Manufacturer	onsemi
Manufacturer Product Number	MC74HC4051ANG
Description	IC MUX 8:1 1000HM 16DIP
Detailed Description	1 Circuit IC Switch 8:1 1000hm 16-PDIP

https://www.DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
MC74HC4051ANG	onsemi
Series:	Product Status:
	Obsolete
Switch Circuit:	Multiplexer/Demultiplexer Circuit:
	8:1
Number of Circuits:	On-State Resistance (Max):
1	1000hm
Channel-to-Channel Matching (ΔRon):	Voltage - Supply, Single (V+):
100hm	2V ~ 6V
Voltage - Supply, Dual (V±):	Switch Time (Ton, Toff) (Max):
±2V~6V	
-3db Bandwidth:	Charge Injection:
80MHz	
Channel Capacitance (CS(off), CD(off)):	Current - Leakage (IS(off)) (Max):
130pF	200nA
Crosstalk:	Operating Temperature:
-	-55°C ~ 125°C (TA)
Mounting Type:	Package / Case:
Through Hole	16-DIP (0.300", 7.62mm)
Supplier Device Package:	Base Product Number:
16-PDIP	74HC4051

Environmental & Export classification

Moisture Sensitivity Level (MSL):	REACH Status:
1 (Unlimited)	REACH Unaffected
ECCN:	HTSUS:
EAR99	8542.39.0001

Analog Multiplexers / Demultiplexers

High-Performance Silicon-Gate CMOS

The MC74HC4051A, MC74HC4052A and MC74HC4053A utilize silicon-gate CMOS technology to achieve fast propagation delays, low ON resistances, and low OFF leakage currents. These analog multiplexers/demultiplexers control analog voltages that may vary across the complete power supply range (from V_{CC} to V_{EE}).

The HC4051A, HC4052A and HC4053A are identical in pinout to the metal-gate MC14051AB, MC14052AB and MC14053AB. The Channel-Select inputs determine which one of the Analog Inputs/Outputs is to be connected, by means of an analog switch, to the Common Output/Input. When the Enable pin is HIGH, all analog switches are turned off.

The Channel-Select and Enable inputs are compatible with standard CMOS outputs; with pullup resistors they are compatible with LSTTL outputs.

These devices have been designed so that the ON resistance (R_{on}) is more linear over input voltage than R_{on} of metal-gate CMOS analog switches.

For a multiplexer/demultiplexer with injection current protection, see HC4851A and HC4852A.

Features

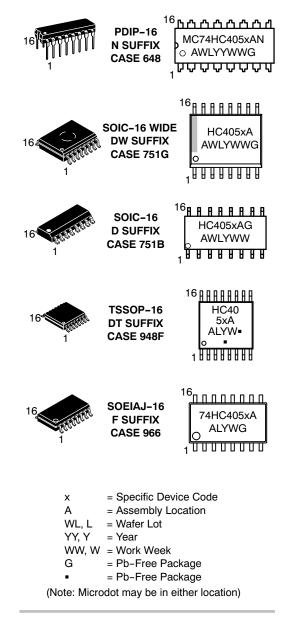
- Fast Switching and Propagation Speeds
- Low Crosstalk Between Switches
- Diode Protection on All Inputs/Outputs
- Analog Power Supply Range ($V_{CC} V_{EE}$) = 2.0 to 12.0 V
- Digital (Control) Power Supply Range (V_{CC} GND) = 2.0 to 6.0 V
- Improved Linearity and Lower ON Resistance Than Metal-Gate Counterparts
- Low Noise
- In Compliance with the Requirements of JEDEC Standard No. 7A
- Chip Complexity: HC4051A 184 FETs or 46 Equivalent Gates HC4052A — 168 FETs or 42 Equivalent Gates HC4053A — 156 FETs or 39 Equivalent Gates
- Pb-Free Packages are Available



ON Semiconductor®

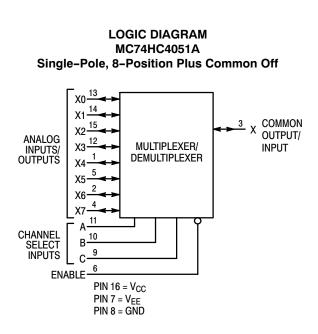
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MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 13 of this data sheet.

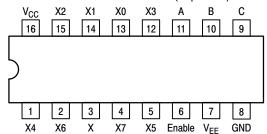


FUNCTION TABLE - MC74HC4051A

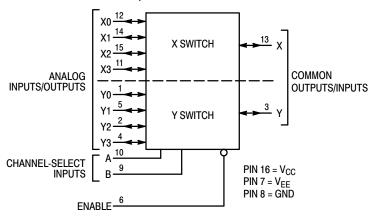
Control Inputs				
	Select		t	
Enable	С	в	Α	ON Channels
L	L	L	Г	X0
L	L	L	н	X1
L	L	Н	L	X2
L	L	Н	н	X3
L	Н	L	L	X4
L	Н	L	н	X5
L	Н	Н	L	X6
L	Н	Н	Н	X7
Н	Х	Х	Х	NONE

X = Don't Care

Pinout: MC74HC4051A (Top View)



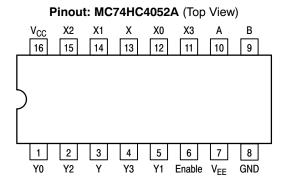


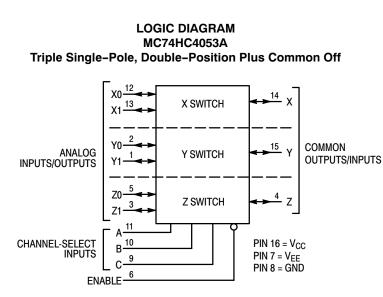


FUNCTION TABLE - MC74HC4052A

Contr	ol Input			
Enable	Sel B	ect A	ON Ch	annels
L L L H	L L H X	L H L H X	Y0 Y1 Y2 Y3 NO	X0 X1 X2 X3

X = Don't Care



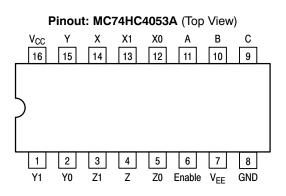


NOTE: This device allows independent control of each switch. Channel-Select Input A controls the X-Switch, Input B controls the Y-Switch and Input C controls the Z-Switch

FUNCTION TABLE - MC74HC4053A

Control Inputs						
Enable	Select C B A			ON	I Chann	els
	•			•		
L	L	L	L	Z0	Y0	X0
L	L	L	Н	Z0	Y0	X1
L	L	н	L	Z0	Y1	X0
L	L	н	Н	Z0	Y1	X1
L	н	L	L	Z1	Y0	X0
L	н	L	Н	Z1	Y0	X1
L	н	н	L	Z1	Y1	X0
L	н	Н	Н	Z1	Y1	X1
н	Х	Х	Х		NONE	

X = Don't Care



MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Positive DC Supply Voltage (Referenced to GND) (Referenced to V _{EE})	- 0.5 to + 7.0 - 0.5 to + 14.0	V
V_{EE}	Negative DC Supply Voltage (Referenced to GND)	- 7.0 to + 5.0	V
V _{IS}	Analog Input Voltage	V _{EE} - 0.5 to V _{CC} + 0.5	V
V _{in}	Digital Input Voltage (Referenced to GND)	-0.5 to V_{CC} + 0.5	V
I	DC Current, Into or Out of Any Pin	± 25	mA
PD	Power Dissipation in Still Air, Plastic DIP† EIAJ/SOIC Package† TSSOP Package†	750 500 450	mW
T _{stg}	Storage Temperature Range	– 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds Plastic DIP, SOIC or TSSOP Package	260	°C

This/evice contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND $\leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$.

Unuse the puts must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C

EIAJ/SOIC Package: - 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

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RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Мах	Unit
V _{CC}	Positive DC Supply Voltage (Refer (Refe	2.0 2.0	6.0 12.0	V	
V _{EE}	Negative DC Supply Voltage, Output GND)	- 6.0	GND	V	
V _{IS}	Analog Input Voltage	V _{EE}	V _{CC}	V	
V _{in}	Digital Input Voltage (Referenced to G	ND)	GND	V _{CC}	V
V _{IO} *	Static or Dynamic Voltage Across Swi	itch		1.2	V
T _A	Operating Temperature Range, All Pa	ckage Types	- 55	+ 125	°C
t _r , t _f	Input Rise/Fall Time (Channel Select or Enable Inputs)	$V_{CC} = 2.0 V V_{CC} = 3.0 V V_{CC} = 4.5 V V_{CC} = 6.0 V$	0 0 0 0	1000 600 500 400	ns

*For voltage drops across switch greater than 1.2V (switch on), excessive V_{CC} current may be drawn; i.e., the current out of the switch may contain both V_{CC} and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND) VEE = GND, Except Where Noted

			V _{cc}	Guara	nteed Lim	nit	
Symbol	Parameter	Condition	v	–55 to 25°C	≤ 85°C	≤125°C	Unit
V _{IH}	Minimum High-Level Input Voltage, Channel-Select or Enable Inputs	R _{on} = Per Spec	2.0 3.0 4.5 6.0	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	V
V _{IL}	Maximum Low-Level Input Voltage, Channel-Select or Enable Inputs	R _{on} = Per Spec	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
l _{in}	Maximum Input Leakage Current, Channel-Select or Enable Inputs	$V_{in} = V_{CC} \text{ or GND},$ $V_{EE} = -6.0 \text{ V}$	6.0	± 0.1	±1.0	± 1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	Channel Select, Enable $V_{IS} = V_{CC}$ or GND; $V_{IO} = 0 V$	6.0 6.0	1 4	10 40	20 80	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

DC CHARACTERISTICS — Analog Section

					Guara	nteed Lin	nit	
Symbol	Parameter	Condition	v _{cc}	V_{EE}	–55 to 25°C	≤85°C	≤125°C	Unit
R _{on}	Maximum "ON" Resistance		4.5 4.5 6.0	0.0 - 4.5 - 6.0	190 120 100	240 150 125	280 170 140	Ω
			4.5 4.5 6.0	0.0 - 4.5 - 6.0	150 100 80	190 125 100	230 140 115	
ΔR_{on}	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package		4.5 4.5 6.0	0.0 - 4.5 - 6.0	30 12 10	35 15 12	40 18 14	Ω
l _{off}	Maximum Off-Channel Leakage Current, Any One Channel		6.0	- 6.0	0.1	0.5	1.0	μΑ
	Maximum Off-ChannelHC4051ALeakage Current,HC4052ACommon ChannelHC4053A	$V_{IO} = V_{CC} - V_{EE};$	6.0 6.0 6.0	- 6.0 - 6.0 - 6.0	0.2 0.1 0.1	2.0 1.0 1.0	4.0 2.0 2.0	
I _{on}	Maximum On-ChannelHC4051ALeakage Current,HC4052AChannel-to-ChannelHC4053A	Switch-to-Switch =	6.0 6.0 6.0	- 6.0 - 6.0 - 6.0	0.2 0.1 0.1	2.0 1.0 1.0	4.0 2.0 2.0	μΑ

AC CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns)

			V _{CC}	Guara	nteed Lim	teed Limit	
Symbol	P	arameter	v	-55 to 25°C	≤85°C	≤125°C	Unit
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Ch (Figure 9)	annel-Select to Analog Output	2.0 3.0 4.5 6.0	270 90 59 45	320 110 79 65	350 125 85 75	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, An (Figure 10)	alog Input to Analog Output	2.0 3.0 4.5 6.0	40 25 12 10	60 30 15 13	70 32 18 15	ns
t _{PLZ} , t _{PHZ}	Maximum Propagation Delay, En (Figure 11)	able to Analog Output	2.0 3.0 4.5 6.0	160 70 48 39	200 95 63 55	220 110 76 63	ns
t _{PZL} , t _{PZH}	Maximum Propagation Delay, En (Figure 11)	able to Analog Output	2.0 3.0 4.5 6.0	245 115 49 39	315 145 69 58	345 155 83 67	ns
C _{in}	Maximum Input Capacitance, Ch	annel-Select or Enable Inputs		10	10	10	pF
C _{I/O}	Maximum Capacitance	Analog I/O		35	35	35	pF
	(All Switches Off)	Common O/I: HC4051A HC4052A HC4053A		130 80 50	130 80 50	130 80 50	
		Feed-through		1.0	1.0	1.0	

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D)

			Typical @ 25°C, V _{CC} = 5.0 V, V _{EE} = 0 V	
C _{PD}	Power Dissipation Capacitance (Figure 13)*	HC4051A HC4052A HC4053A		pF

* Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

ADDITIONAL APPLICATION CHARACTERISTICS (GND = 0 V)

			V _{CC}	V _{EE}		Limit*		
Symbol	Parameter	Condition	v	V	25°C		Unit	
BW	Maximum On-Channel Bandwidth or Minimum Frequency Response (Figure 6)	$ f_{in} = 1 MHz Sine Wave; Adjust f_{in} Voltage to Obtain 0dBm at V_{OS}; Increase f_{in} Frequency Until dB Meter Reads -3dB; R_L = 50\Omega, C_L = 10 pF $	2.25 4.50 6.00	-2.25 -4.50 -6.00	'51 80 80 80	'52 95 95 95	'53 120 120 120	MHz
-	Off-Channel Feed-through Isolation (Figure 7)	$ \begin{array}{l} f_{in} = \text{Sine Wave; Adjust } f_{in} \text{ Voltage to} \\ \text{Obtain 0dBm at } \text{V}_{\text{IS}} \\ f_{in} = 10 \text{kHz}, \ \text{R}_{\text{L}} = 600 \Omega, \ \text{C}_{\text{L}} = 50 \text{pF} \end{array} $	2.25 4.50 6.00	-2.25 -4.50 -6.00		-50 -50 -50		dB
		f _{in} = 1.0MHz, R _L = 50Ω, C _L = 10pF	2.25 4.50 6.00	-2.25 -4.50 -6.00		-40 -40 -40		
-	Feedthrough Noise. Channel-Select Input to Common I/O (Figure 8)	$ \begin{array}{l} V_{in} \leq 1 MHz \; \text{Square Wave } (t_r = t_f = 6 \text{ns}); \\ \text{Adjust } R_L \; \text{at Setup so that } I_S = 0 \text{A}; \\ \text{Enable = GND} R_L = 600 \Omega, \; C_L = 50 \text{pF} \end{array} $	2.25 4.50 6.00	-2.25 -4.50 -6.00		25 105 135		mV _{PP}
		$R_L = 10k\Omega$, $C_L = 10pF$	2.25 4.50 6.00	-2.25 -4.50 -6.00		35 145 190		
-	Crosstalk Between Any Two Switches (Figure 12) (Test does not apply to HC4051A)	$ \begin{array}{l} f_{in} = Sine \mbox{ Wave; Adjust } f_{in} \mbox{ Voltage to} \\ Obtain \mbox{ 0dBm at } V_{IS} \\ f_{in} = 10 \mbox{ Hz, } R_L = 600 \Omega, \mbox{ C}_L = 50 \mbox{ pF} \end{array} $	2.25 4.50 6.00	-2.25 -4.50 -6.00		-50 -50 -50		dB
		f _{in} = 1.0MHz, R _L = 50Ω, C _L = 10pF	2.25 4.50 6.00	-2.25 -4.50 -6.00		-60 -60 -60		
THD	Total Harmonic Distortion (Figure 14)	$\label{eq:fin} \begin{array}{l} f_{in} = 1 \text{kHz}, \ R_L = 10 \text{k}\Omega, \ C_L = 50 \text{pF} \\ \text{THD} = \text{THD}_{measured} - \text{THD}_{source} \\ V_{IS} = 4.0 \text{V}_{PP} \ \text{sine wave} \\ V_{IS} = 8.0 \text{V}_{PP} \ \text{sine wave} \\ V_{IS} = 11.0 \text{V}_{PP} \ \text{sine wave} \end{array}$	2.25 4.50 6.00	-2.25 -4.50 -6.00		0.10 0.08 0.05		%

*Limits not tested. Determined by design and verified by qualification.

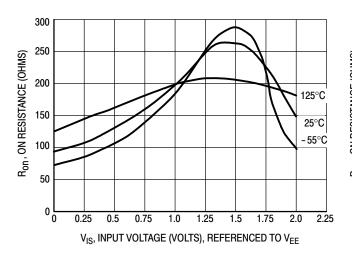
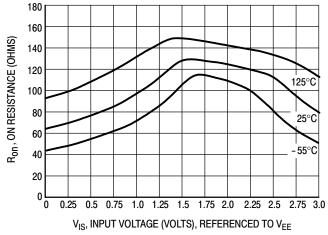
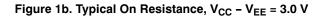


Figure 1a. Typical On Resistance, V_{CC} – V_{EE} = 2.0 V





MC74HC4051A, MC74HC4052A, MC74HC4053A

105

90

75

60

45

30

15

0

0.5 1.0 1.5

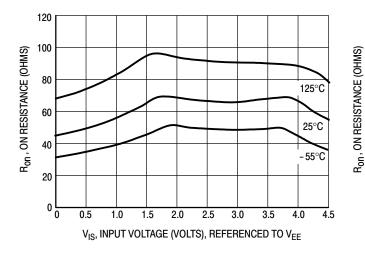


Figure 1c. Typical On Resistance, $V_{CC} - V_{EE} = 4.5 V$

Figure 1d. Typical On Resistance, $V_{CC} - V_{EE} = 6.0 V$

VIS, INPUT VOLTAGE (VOLTS), REFERENCED TO VEE

2.0 2.5 3.0 3.5 4.0 4.5 5.0 5.5 6.0

125°C

25°C

-55°C

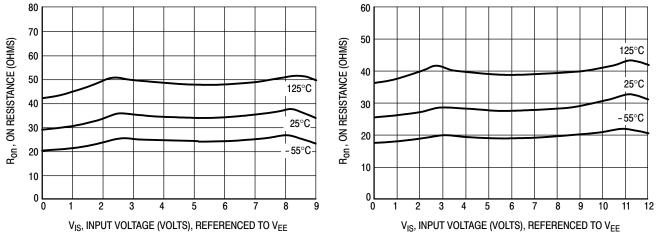


Figure 1e. Typical On Resistance, V_{CC} – V_{EE} = 9.0 V

Figure 1f. Typical On Resistance, V_{CC} – V_{EE} = 12.0 V

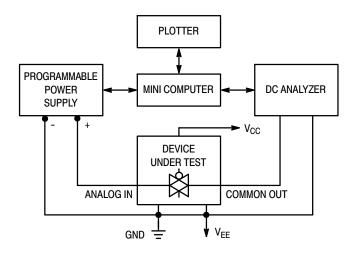


Figure 2. On Resistance Test Set-Up

MC74HC4051ANG onsemi IC MUX 8:1 1000HM 16DIP

MC74HC4051A, MC74HC4052A, MC74HC4053A

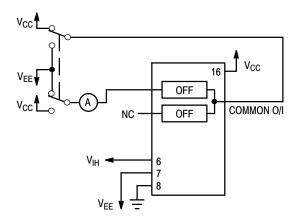
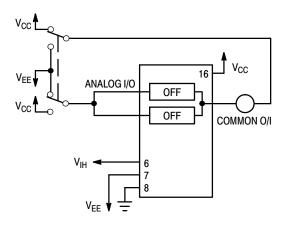
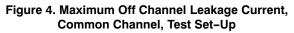


Figure 3. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up





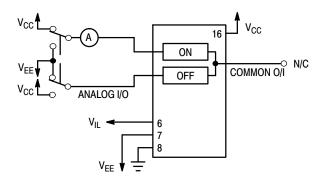
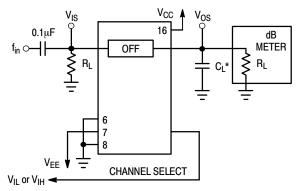


Figure 5. Maximum On Channel Leakage Current, Channel to Channel, Test Set-Up



*Includes all probe and jig capacitance



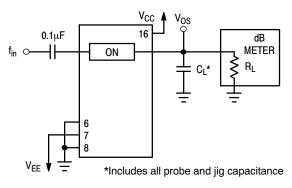
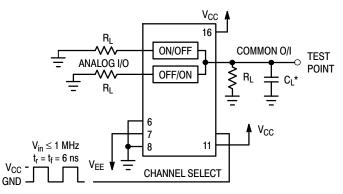
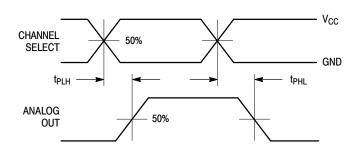


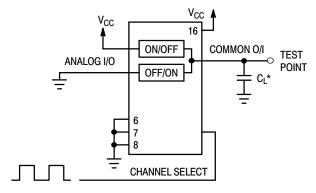
Figure 6. Maximum On Channel Bandwidth, Test Set-Up



*Includes all probe and jig capacitance

Figure 8. Feedthrough Noise, Channel Select to Common Out, Test Set–Up





*Includes all probe and jig capacitance





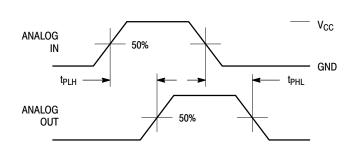
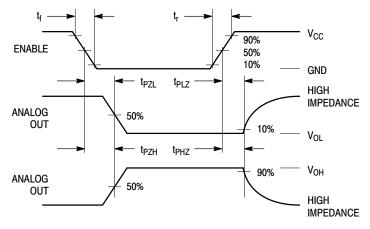
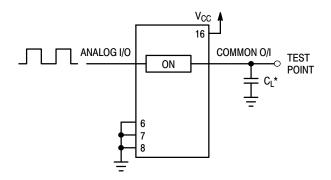


Figure 10a. Propagation Delays, Analog In to Analog Out

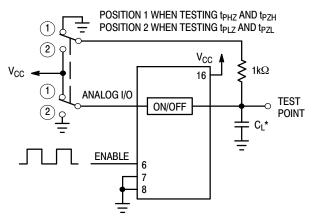


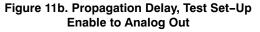


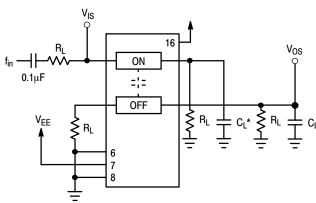


*Includes all probe and jig capacitance

Figure 10b. Propagation Delay, Test Set-Up Analog In to Analog Out

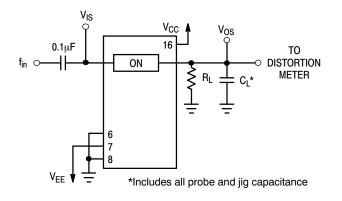






*Includes all probe and jig capacitance

Figure 12. Crosstalk Between Any Two Switches, Test Set-Up





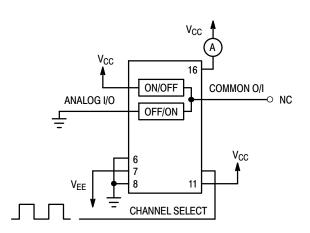


Figure 13. Power Dissipation Capacitance, Test Set–Up

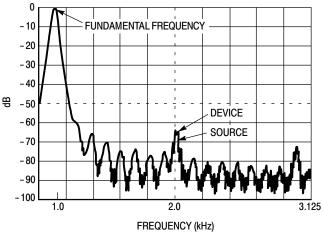


Figure 14b. Plot, Harmonic Distortion

APPLICATIONS INFORMATION

The Channel Select and Enable control pins should be at V_{CC} or GND logic levels. V_{CC} being recognized as a logic high and GND being recognized as a logic low. In this example:

$$V_{CC} = +5V = \text{logic high}$$

GND = 0V = logic low

The maximum analog voltage swings are determined by the supply voltages V_{CC} and V_{EE} . The positive peak analog voltage should not exceed V_{CC} . Similarly, the negative peak analog voltage should not go below V_{EE} . In this example, the difference between V_{CC} and V_{EE} is ten volts. Therefore, using the configuration of Figure 15, a maximum analog signal of ten volts peak-to-peak can be controlled. Unused analog inputs/outputs may be left floating (i.e., not connected). However, tying unused analog inputs and outputs to V_{CC} or GND through a low value resistor helps minimize crosstalk and feed-through noise that may be picked up by an unused switch.

Although used here, balanced supplies are not a requirement. The only constraints on the power supplies are that:

$$\begin{split} V_{CC} - GND &= 2 \text{ to } 6 \text{ volts} \\ V_{EE} - GND &= 0 \text{ to } -6 \text{ volts} \\ V_{CC} - V_{EE} &= 2 \text{ to } 12 \text{ volts} \\ \text{ and } V_{EE} &\leq GND \end{split}$$

When voltage transients above V_{CC} and/or below V_{EE} are anticipated on the analog channels, external Germanium or Schottky diodes (D_x) are recommended as shown in Figure 16. These diodes should be able to absorb the maximum anticipated current surges during clipping.

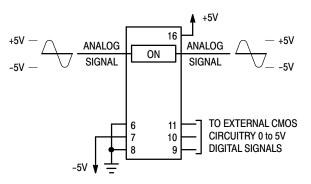


Figure 15. Application Example

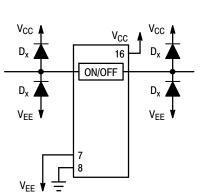
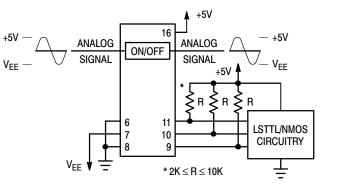
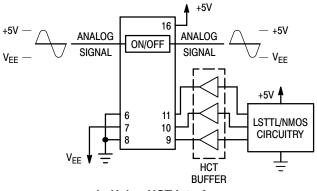


Figure 16. External Germanium or **Schottky Clipping Diodes**



a. Using Pull-Up Resistors



b. Using HCT Interface

Figure 17. Interfacing LSTTL/NMOS to CMOS Inputs

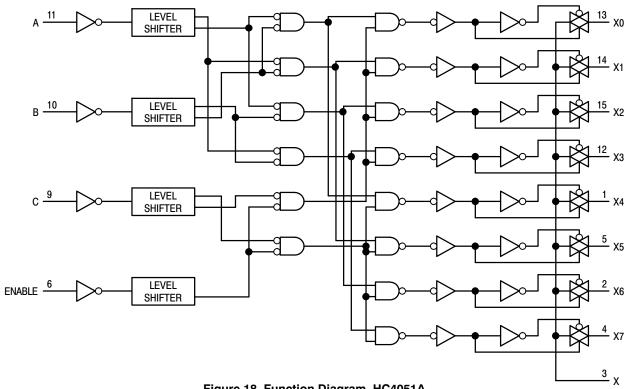
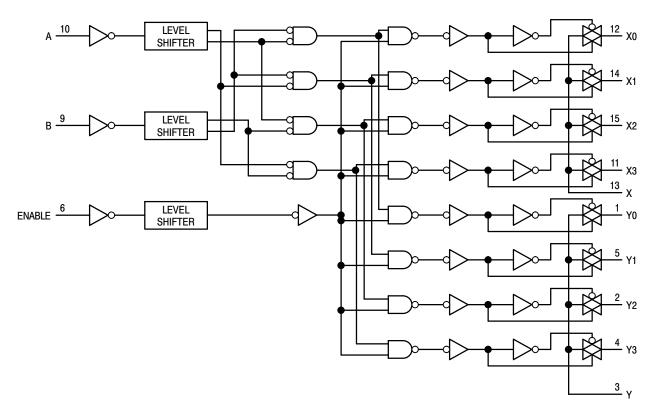


Figure 18. Function Diagram, HC4051A

MC74HC4051A, MC74HC4052A, MC74HC4053A





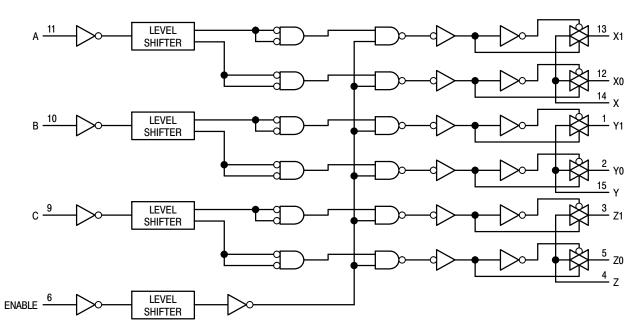


Figure 20. Function Diagram, HC4053A

ORDERING INFORMATION

Device	Package	Shipping [†]	
MC74HC4051AN	PDIP-16	500 Units / Box	
MC74HC4051ANG	PDIP-16 (Pb-Free)	500 Units / Box	
MC74HC4051AD	SOIC-16	48 Units / Rail	
MC74HC4051ADG	SOIC-16 (Pb-Free)	48 Units / Rail	
MC74HC4051ADR2	SOIC-16	2500 Units / Tape & Reel	
MC74HC4051ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel	
MC74HC4051ADT	TSSOP-16*	96 Units / Rail	
MC74HC4051ADTG	TSSOP-16*	96 Units / Rail	
MC74HC4051ADTR2	TSSOP-16*	2500 Units / Tape & Reel	
MC74HC4051ADTR2G	TSSOP-16*	2500 Units / Tape & Reel	
MC74HC4051ADW	SOIC-16 WIDE	48 Units / Rail	
MC74HC4051ADWG	SOIC-16 WIDE (Pb-Free)	48 Units / Rail	
MC74HC4051ADWR2	SOIC-16 WIDE	1000 Units / Tape & Reel	
MC74HC4051ADWR2G	SOIC-16 WIDE (Pb-Free)	1000 Units / Tape & Reel	
MC74HC4051AFEL	SOEIAJ-16	2000 Units / Tape & Reel	
MC74HC4051AFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel	
MC74HC4052AN	PDIP-16	500 Units / Box	
MC74HC4052ANG	PDIP-16 (Pb-Free)	500 Units / Box	
MC74HC4052AD	SOIC-16	48 Units / Rail	
MC74HC4052ADG	SOIC-16 (Pb-Free)	48 Units / Rail	
MC74HC4052ADR2	SOIC-16	2500 Units / Tape & Reel	
MC74HC4052ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel	
MC74HC4052ADT	TSSOP-16*	96 Units / Rail	
MC74HC4052ADTG	TSSOP-16*	96 Units / Rail	
MC74HC4052ADTR2	TSSOP-16*	2500 Units / Tape & Reel	
MC74HC4052ADTR2G	TSSOP-16*	2500 Units / Tape & Reel	
MC74HC4052ADW	SOIC-16 WIDE	48 Units / Rail	
MC74HC4052ADWG	SOIC-16 WIDE (Pb-Free)	48 Units / Rail	
MC74HC4052ADWR2	SOIC-16 WIDE	1000 Units / Tape & Reel	
MC74HC4052ADWR2G	SOIC-16 WIDE (Pb-Free)	1000 Units / Tape & Reel	
MC74HC4052AFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
 *This package is inherently Pb-Free.

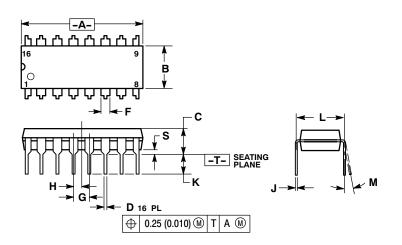
ORDERING INFORMATION

Device	Package	Shipping [†]		
MC74HC4053AN	PDIP-16	500 Units / Box		
MC74HC4053ANG	PDIP-16 (Pb-Free)	500 Units / Box		
MC74HC4053AD	SOIC-16	48 Units / Rail		
MC74HC4053ADG	SOIC-16 (Pb-Free)	48 Units / Rail		
MC74HC4053ADR2	SOIC-16	2500 Units / Tape & Reel		
MC74HC4053ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel		
MC74HC4053ADT	TSSOP-16*	96 Units / Rail		
MC74HC4053ADTG	TSSOP-16*	96 Units / Rail		
MC74HC4053ADTR2	TSSOP-16*	2500 Units / Tape & Reel		
MC74HC4053ADTR2G	TSSOP-16*	2500 Units / Tape & Reel		
MC74HC4053ADW	SOIC-16 WIDE	48 Units / Rail		
MC74HC4053ADWG	SOIC-16 WIDE (Pb-Free)	48 Units / Rail		
MC74HC4053ADWR2	SOIC-16 WIDE	1000 Units / Tape & Reel		
MC74HC4053ADWR2G	SOIC-16 WIDE (Pb-Free)	1000 Units / Tape & Reel		
MC74HC4053AF	SOEIAJ-16	50 Units / Rail		
MC74HC4053AFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail		
MC74HC4053AFEL	SOEIAJ-16	2000 Units / Tape & Reel		
MC74HC4053AFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel		

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
 *This package is inherently Pb-Free.

PACKAGE DIMENSIONS



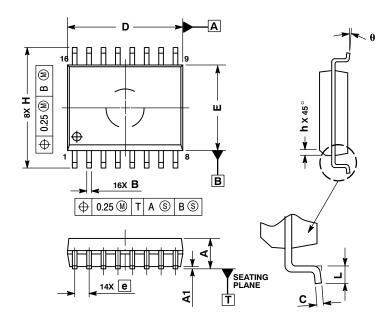


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- DIMENSIONING AND TOZEPANCING P ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE MOLD FLASH. 2.
- З.
- 4
- 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
κ	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0 °	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

SOIC-16 WIDE **DW SUFFIX** CASE 751G-03 ISSUE C



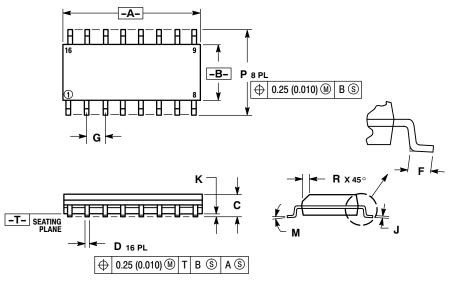
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- NOTES:
 DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	10.15	10.45		
Е	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
q	0 °	7 °		

PACKAGE DIMENSIONS

SOIC-16 **D SUFFIX** CASE 751B-05 ISSUE K

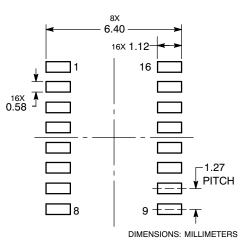


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2. 3.
- CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 4. 5.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
М	0 °	7°	0°	7°
Ρ	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

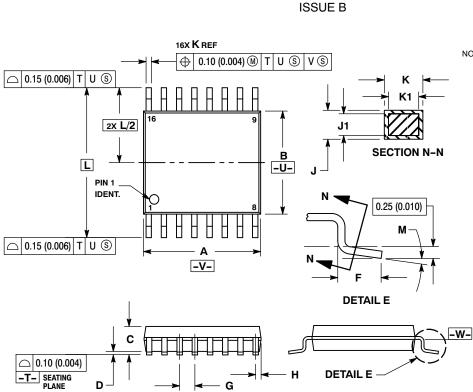
SOLDERING FOOTPRINT*



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PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** CASE 948F-01



G

D

NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

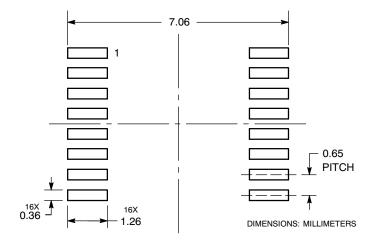
20NTROLLING DIMENSION: MILLIMETER. BIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT

MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. BUMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. BIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. SLAUKABLE DAMBAR PROTRUSION. SLAUKABLE DAMBAH PHO I RUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

TERMINAL NUMBERS ARE SHOWN FOR DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252 BSC	
М	0 °	8 °	0 °	8 °

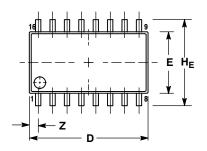
SOLDERING FOOTPRINT*

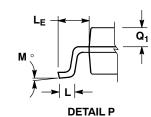


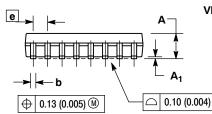
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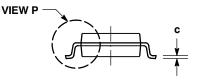
PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** CASE 966-01 **ISSUE A**









NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER

DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

4CERMINAL NUMBERS ARE SHOWN FOR

ALEMNINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 3THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	MILLIMETERS INCHES		
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

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